

ABSTRACT

This invention provides a process for electroless copper plating without using formaldehyde and an electroless copper plating solution which is used in the process. To this end, there is disclosed a process for electroless copper plating, which treatment comprises depositing a palladium or palladium-tin catalyst on a resin substrate, and then treating said resin substrate having the catalyst deposited thereon with a formaldehyde-free electroless copper plating solution that contains copper ions and a reducing agent, wherein the need for an accelerating treatment of a catalyst after said catalyst depositing treatment is obviated. The productivity of a copper-resin composite material is dramatically enhanced by the process of the present invention, because a copper thin layer can be formed on the resin substrate in a short time, even if an accelerating treatment for a catalyst is not performed in a separate process.